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Dual N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^d	Q _g (Typ.)		
40	0.0145 at V _{GS} = 10 V	28	17 nC		
	0.0185 at V _{GS} = 4.5 V	20	17110		

FEATURES

- DT-Trench Power MOSFET
- 100 % $\rm R_{\rm g}$ and UIS Tested

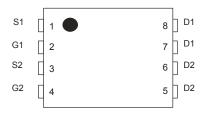
Pb free

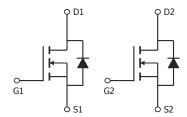
RoHS

APPLICATIONS

- · Backlight inverter for LCD displays
- DC/DC converter

Top View





Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	40	V	
Gate-Source Voltage		V _{GS}	± 20	_ v
	T _C = 25 °C		28 ^a	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	1 . –	20	7
Continuous Diam Current (1) = 130 °C)	T _A = 25 °C	l _D	14 ^{b, c}	7
	T _A = 70 °C	1	8 ^{b, c}	A
Pulsed Drain Current		I _{DM}	110	
0 " 0 5 5 1 0 1	T _C = 25 °C	La	28	7
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	13 ^{b, c}	1
Avalanche Current		I _{AS}	26	7
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	58	mJ
Maximum Power Dissipation	T _C = 25 °C		23	
	T _C = 70 °C	P _D	14.7	w
	T _A = 25 °C] 'D [1.7 ^{b, c}	v
	T _A = 70 °C		1.1 ^{b, c}	7
Operating Junction and Storage Temperature Rang	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	5	10	- C/VV	

Notes

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c = 10 s
- d. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}.$



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		55		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = 230 μΛ		- 6.3			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} = 0 V			1	110	
		$V_{DS} = 32 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	36			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 10 \text{A}$		0.0145	0.017	Ω	
	US(on)	V _{GS} = 4.5 V, I _D = 5A		0.0185	0.025		
Forward Transconductance ^a	9 _{fs}	V _{DS} =5 V, I _D = 10A		40		S	
Dynamic ^b				•			
Input Capacitance	C _{iss}			1005		pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		112			
Reverse Transfer Capacitance	C _{rss}			31		Ī	
Total Gate Charge	Qg			17		20	
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		4.5		nC	
Gate-Drain Charge	Q_{gd}			6.8		Ī	
Gate Resistance	R _g	f = 1 MHz		3.0		Ω	
Turn-On Delay Time	t _{d(on)}			10			
Rise Time	t _r	V_{DD} = 20 V, R_L = 5.4 Ω		28		ns	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		45			
Fall Time	t _f			23			
Drain-Source Body Diode Characteris	tics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			28	А	
Pulse Diode Forward Current ^a	I _{SM}				110	A	
Body Diode Voltage	V _{SD}	I _S = 2 A		0.7	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	L = 5.5 A dl/dt = 100 A/up T = 25.00		25		ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 5.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		55		nC	

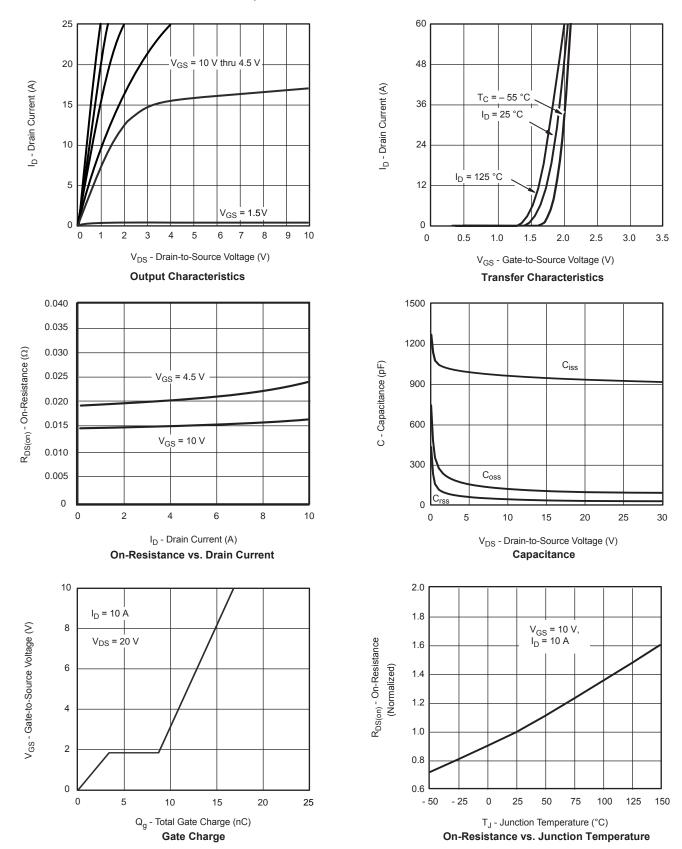
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

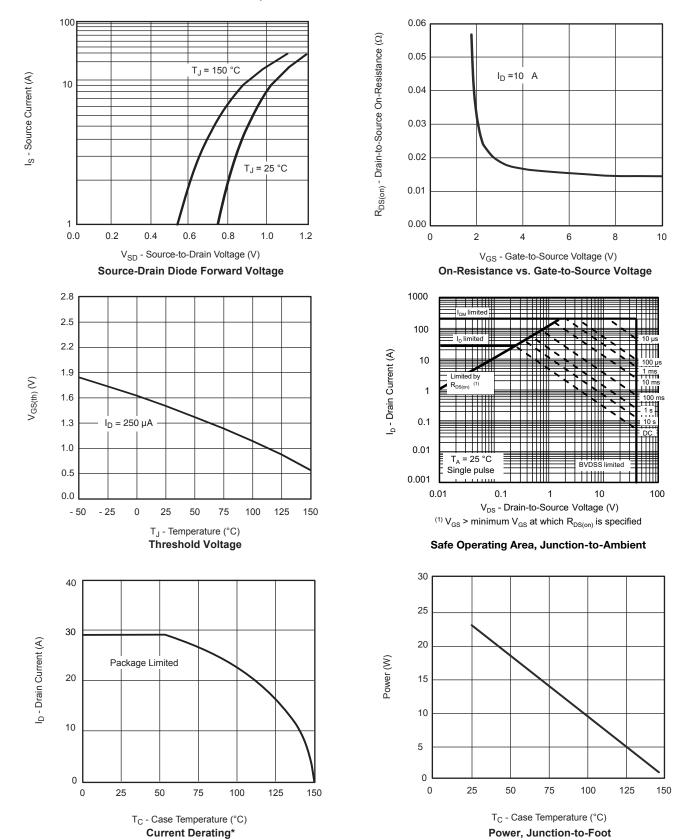


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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